



Integrated Circuit Packaging, Assembly and Interconnections (Springer Series in Advanced Microelectronics)

By William Greig

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Reviewing the various IC packaging, assembly, and interconnection technologies, this professional reference provides an overview of the materials and the processes, as well as the trends and available options that encompass electronic manufacturing. It covers both the technical issues and touches on some of the reliability concerns with the various technologies applicable to packaging and assembly of the IC. The book discusses the various packaging approaches, assembly options, and essential manufacturing technologies, among other relevant topics.

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Editorial Review

From the Back Cover

Integrated Circuit Packaging, Assembly and Interconnections is intended as a multi-purpose text, serving individuals looking for an introduction, or a review, or an update of the various IC packaging, assembly, and interconnection technologies. To this end, it provides an overview of the materials and the processes, as well as the trends and available options that encompass electronic manufacturing. It covers both the technical issues and touches on some of the reliability concerns with the various technologies applicable to packaging and assembly of the IC.

The focus is on the electronic manufacturing process which, in its simplest form, involves assembly of the IC into a package or interconnect substrate or board. The book discusses the various packaging approaches available, namely, single chip, multichip, and Chip On Board; the assembly options, chip & wire, tape automated bonding, and flip chip; and the essential high density package/substrate manufacturing technologies, thin film, thick film, cofired ceramic, and laminate printed wiring board (PWB) processes. Included also is a discussion of high density PWBs using build up/sequential processes.

This material will provide a suitable knowledge-base essential for individuals who have the need or interest in understanding the basics of electronic manufacturing.

About the Author

About the Author

A graduate of Fordham University with a BS in Physics Bill has had extensive experience in Microelectronics covering semiconductor processing and assembly, Hybrid Circuits, and PWB fabrication and assembly. He began his career with RCA Semiconductor Division and subsequently worked for General Electric and Lockheed Electronics. While at RCA he was awarded six U.S. patents covering wafer processing and semiconductor assembly. At General Electric he was a staff engineer and consultant for hybrid circuits and PWB manufacturing.

As Manager of Advanced Development at Lockheed, he was directly responsible for the design, construction, and operation of a state of the art Microelectronic Packaging facility supporting research, development, and manufacture of advanced hybrid circuits and multichip modules.

He became an independent consultant in 1988. His clients have included material suppliers, assembly equipment manufacturers, and component manufacturers.

His consulting activities has included work at NASA Headquarters in Washington D.C. where he provided technical expertise and assistance in developing an Advanced Integrated Circuit Packaging and Assembly Program.

Bill specializes in packaging and assembly, focusing on high density substrate manufacturing, and chip assembly including flip chip and chip scale packaging.

His company offers assistance in technology assessment and implementation, and specializes in technical audits of manufacturing operations directed towards yield improvement and reliability enhancement.

He has developed several educational and training courses which are offered at various national and international symposia and on-site presentations.

He is an active member of IMAPS where he is a Fellow of the Society and Past President of the Garden State Chapter.

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